

NEW

MET-MOUNT EPOXY MOUNTING SYSTEMS



MET-MOUNT 1

6 HRS.

A clear, fast curing epoxy system with moderate viscosity and hardness, low shrinkage, and excellent edge retention. Cures to 80 Shore D in 6 hours at room temperature. Used in standard application not requiring penetration into pores or fine features. Mixing ratio 4:1 by volume. 100g / 23.4g by weight. (Equivalent to Epoxy Cure 2)



MET-MOUNT 2

9 HRS.



A clear, epoxy system with very low viscosity, moderate shrinkage and hardness. Cures to 76 Shore D in 9 hours at room temperature. Used for applications when penetration into pores and fine features is important. (heat sensitive materials such as electronic boards) Mixing ratio 2:1 by volume. 100g / 45g by weight. (Equivalent to Epo Thin 2)



MET-MOUNT 3

2 HRS.

A clear, fast curing epoxy system with low viscosity, moderate shrinkage and hardness. Cures to 80 Shore D in 100-120 minutes at room temperature. Used for applications where speed is of the essence. Mixing ratio 5:1 by volume. 100g / 20g by weight. (Equivalent to Epo Kwick)



MET-MOUNT 4

1.5 HRS.



A clear yellowish heat curing epoxy system with very low viscosity and shrinkage. Excellent edge retention and penetration of small pores and features. Cures to 80 Shore D in 90 minutes with heat. Used for application requiring penetration into pores or fine features. Mixing ratio 4:1 by volume. 100g / 20.6g by weight. (Equivalent to Epo Heat)



MET-VAC

Vacuum impregnation system. Can hold up to 8 round samples



NICKEL CONDUCTIVE FILLER

Used for Nickel based castable mounts when doing SEM, EDS work. Add to Metlab Epoxies & Acrylics to make mounts conductive.



COLD MOUNTING SUPPLIES

Plastic re-usable molds, silicon rubber molds, metal and plastic clips, stir sticks and mold release.

Contact sales@metlabcorp.com today for your FREE sample.